

# Process Change Notice PCN2002-10

## XC9500XL 3.3V CPLD – Device Transition

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(Not applicable to XC9500 or XC9500XV product families)

**Overview:** This notification is to inform you of a device transition for the XC9500XL 3.3 volt CPLD family. The metallization layers in the XC9500XL family will be reduced in dimension; however, the transistor dimensions and number of metallization layers will remain unchanged. Both the original and new masks are fabricated on a 0.35 $\mu$ m 4-layer metal Flash CMOS process at UMC, Taiwan. Since the transistor size, power supply voltage, and number of metallization layers remain unchanged, there will be minimal impact on the form, fit and function of the XC9500XL devices. The new mask is also programming file compatible with the original mask. There will be no changes to the datasheet specifications as a result of this process change.

This change is being made to improve Xilinx's ability to support this product effectively and to accommodate our customers' high volume demands.

Upon availability of production units from the new mask in December 2002, customers may expect to receive the XC9500XL devices (XC9536XL, XC9572XL, XC95144XL, and XC95288XL) manufactured with either the original or new mask until transition to the new mask is completed.

**Key Dates:** Evaluation samples of the XC9500XL fabricated with the new mask are now available. Use special ordering number SCD0768 to obtain these evaluation samples. For example, the new mask version of the XC9572XL-10PC44C can be ordered as XC9572XL-10PC44C**0768**. Production devices of the XC9500XL fabricated with the new mask will be available in December 2002. Last time orders for the original mask revision product may be placed up to March 12, 2003, by using SCD0696. Please note that such orders will be non-cancellable and non-returnable. Devices will be built-to-order and may involve longer than normal leadtimes. Last time shipments for these orders will occur on or before September 12, 2003. Only the new mask revision material will be available after this date.

Summary of Key Dates:

Evaluation Period:	September 12 – December 12, 2002
Production Shipments Begin:	December 13, 2002
Last Time Buy for Original Mask:	March 12, 2003
Last Time Ship for Original Mask:	September 12, 2003

Please contact your [Xilinx Sales Representative](#) to obtain qualification samples or production devices.

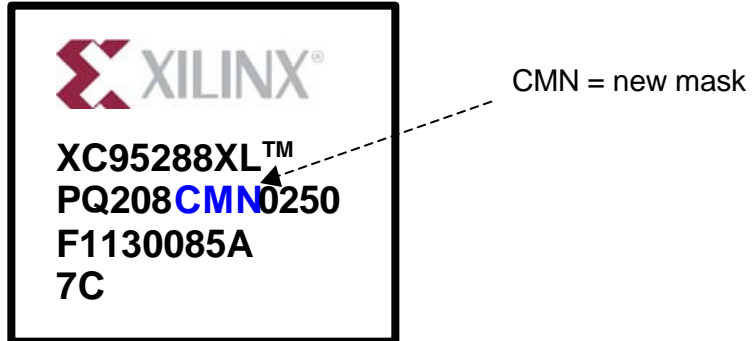
**Qualification Data:** The following is the qualification data for the new mask:

Lot #	Part	Package	Test	Quantity	Hours/Cy	Fails	Status
X0011LT	XC95288XL	PQ208	HTOL	76	24	0	continue
			@125°C		48	0	continue
					256	0	continue
					500	0	continue
					1000	0	complete
X0583LT	XC95288XL	PQ208	HTOL	76	500	0	complete
			@125°C				
X8689MS	XC95144XL	CS144	THB	76	48	0	continue
			@85°C / 85%RH		256	0	continue
					500	0	continue
					1000	0	complete
X8687TC	XC95144XL	TQ144	Temp Cycle	76	500	0	complete
			@-65°C / +150°C				
			Condition C				

**Traceability:**

These devices can be distinguished by a 3-letter code located on the second line of the package topmark in between the package/pin code and the datecode. The 3-letter code will be “CMN” for product manufactured with the new mask. See example below.

Example of a package topmark:



**Response and Contact:** Please contact your [Xilinx Sales Representative](#) to obtain evaluation samples or production devices. For additional information or questions, please send email to the Quality Assurance group at [pcn@xilinx.com](mailto:pcn@xilinx.com), or directly by fax at (408) 369-1718.

Per JEDEC Standard JESD46-B, customers should acknowledge receipt of the PCN within 30 days of delivery of the PCN. Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change. After acknowledgement, lack of additional response within the 90-day period constitutes acceptance of the change.